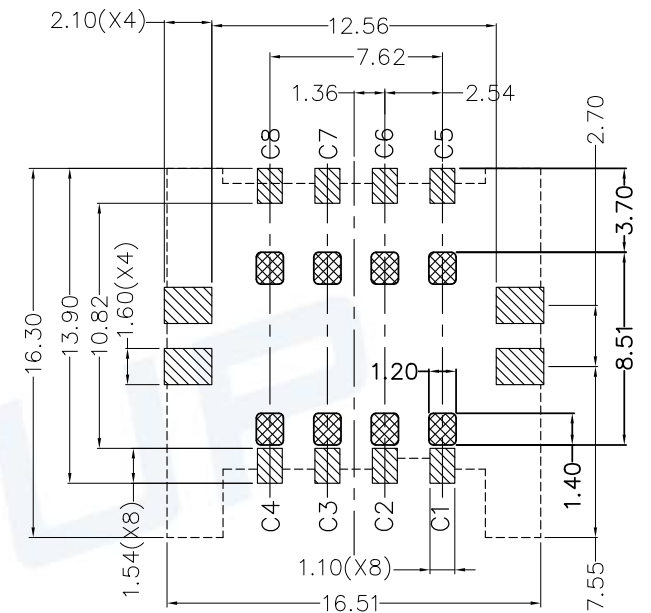
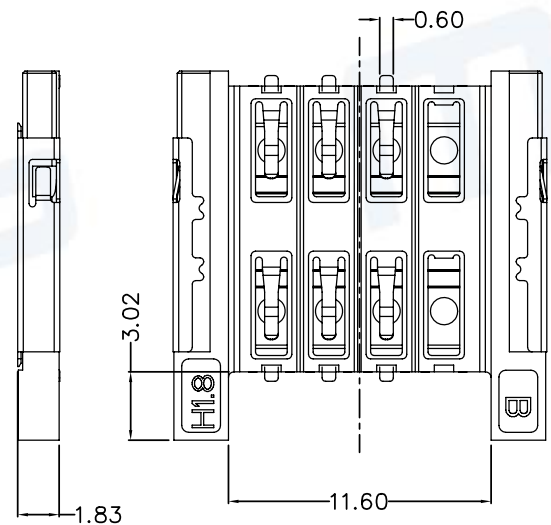
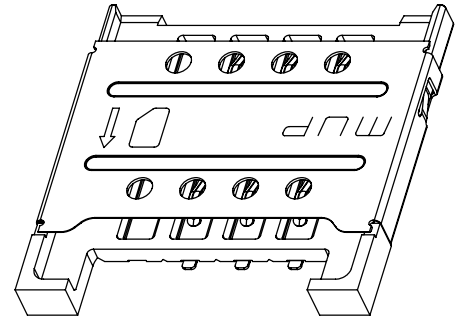
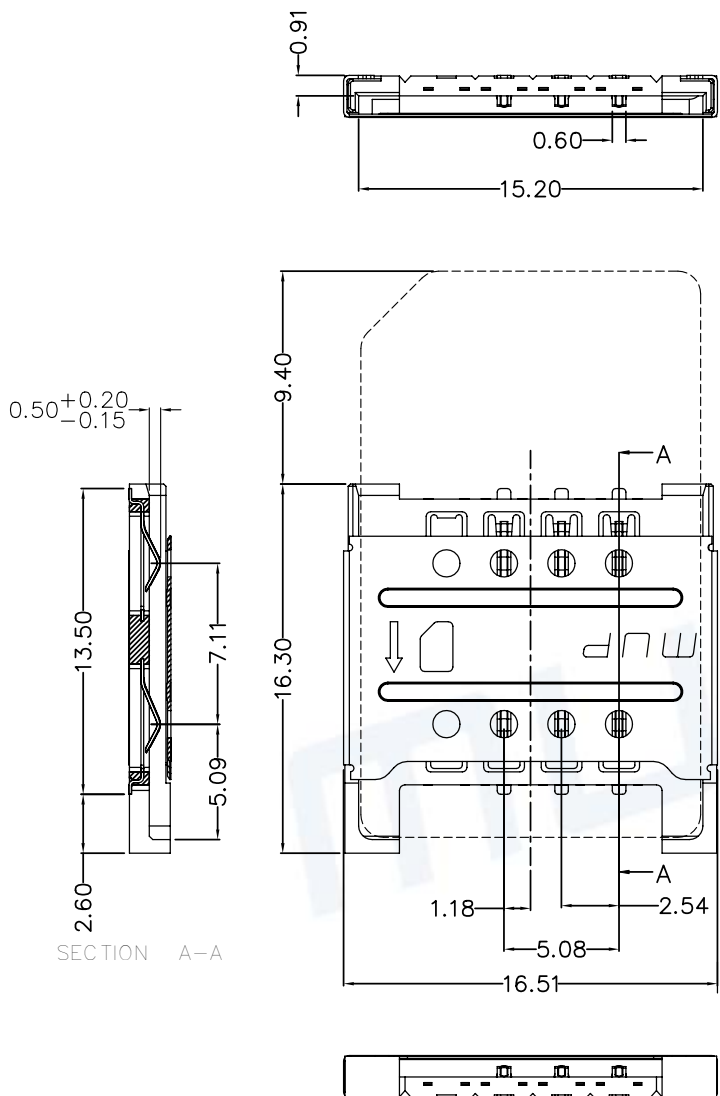


REV.	DESCRIPTION OF REVISIONS	APPR.	CHKD.	DRAW.	DATE
▲	NEW			Jimmy	2017/5/10
▲	Original Model C708-5			HXR	2023/10/27



RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

PAD AREA
 KEEP AREA

TECHNICAL CHARACTERISTICS

1.General Characteristics
Dimensions: 16.51X16.30WX1.80H mm
Weight: Approx. g
Durability: 5,000 cycles min.

2.Electrical Characteristics
Contact resistance: 50mΩ typical, 100mΩ max
Insulation resistance: >1000MΩ/500V DC

3.Solderability
Vaporphase: 215°C, 30sec. Max
IR reflow: 250°C, 5sec. Max
Manual soldering: 370°C, 3sec. Max

4.Environmental Characteristics
Operating temperature: -40°C~+85°C
Operating humidity: 10%~+95%RH

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area: Gold plated
3	SHELL	1	Stainless Steel	SMT area: Gold plated

Unless otherwise specified, other tolerance are:

X	±0.35	X*	±5*
X.X	±0.25	X.X*	±4*
X.XX	±0.15	X.XX*	±3*
X.XXX	±0.10	X.XXX*	±2*

MUP MUP INDUSTRIAL CO.,LTD.

NAME: **SIM Card Connector**
MODEL NO: **MUP-C708-05**
TYPE: **H1.80 Without post 6P(Long shell)**

PROJ.	UNIT	SCALE	DRAWN	Jimmy 2017/5/10	DWG NO.:	DWG-C708-05-01
	mm	1:1	CHECKED	Sean 2017/5/10	SHEET	1/1
CUSTOMER DRAWING			APPROVAL	Simon 2017/5/10	REVISION	2

